

## High-Tensile Alloyed Copper Foil

Catlog Number: BMBCC-0017

### • Description

Reinforced copper substrate designed to withstand the high mechanical stresses of calendaring and active material expansion.

### • Basic Information

Substrate Material: Copper Alloy

Purity (%):  $\geq 99.5$

Thickness ( $\mu\text{m}$ ): 8

Width (mm): 300

Areal Density ( $\text{g}/\text{m}^2$ ): 70.0 - 72.0

Tensile Strength (MPa): 500 - 750

Elongation (%):  $\geq 1.5$

Surface Finish: Matte Finish

Surface Roughness ( $R_a$ ,  $\mu\text{m}$ ):  $\leq 0.40$

Electrical Resistivity ( $\Omega\cdot\text{m}$ ):  $2.5 \times 10^{-8}$

Thermal Conductivity ( $\text{W}/\text{m}\cdot\text{K}$ ): 320

Melting Point ( $^{\circ}\text{C}$ ): 1050

Oxidation Resistance (Temp/Time):  $300^{\circ}\text{C}$  / 60min

Coating Type: N/A

Coating Thickness ( $\mu\text{m}$ ): N/A

Core ID (mm): 76

Standard Length (m): 200

Operating Voltage Range (V): 0.0 - 2.5

Application Compatibility: Solid-State Anode

Storage Requirements: Dry Storage

Form Factor: Roll

Hydrophilic Properties: Mechanical Strength

Compliance / Grade: Battery Grade

 For Research or Industrial Raw Materials, Not For Personal Medical Use!